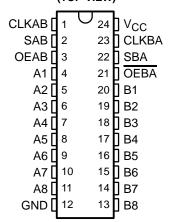
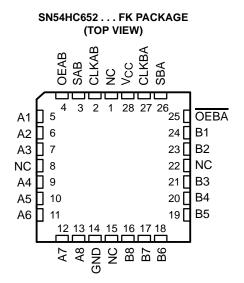
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 11 ns
- ±6-mA Output Drive at 5 V

SN54HC652...JT OR W PACKAGE SN74HC652...DW OR NT PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Independent Registers and Enables for A and B Buses
- Multiplexed Real-Time and Stored Data
- True Data Paths



NC - No internal connection

description/ordering information

The 'HC652 devices consist of bus-transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output-enable (OEAB and OEBA) inputs are provided to control the transceiver functions. Select-control (SAB and SBA) inputs are provided to select real-time or stored-data transfer. A low input level selects real-time data, and a high input level selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with these devices.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – NT	Tube	SN74HC652NT	SN74HC652NT
–40°C to 85°C	SOIC - DW	Tube	SN74HC652DW	HC652
	SOIC - DW	Tape and reel	SN74HC652DWR	HC052
	CDIP – JT	Tube	SNJ54HC652JT	SNJ54HC652JT
−55°C to 125°C	CFP – W	Tube	SNJ54HC652W	SNJ54HC652W
	LCCC – FK	Tube	SNJ54HC652FK	SNJ54HC652FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54HC652, SN74HC652 **OCTAL BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS

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description/ordering information (continued)

Data on the A or B data bus, or both, can be stored in the internal D-type flip-flops by low-to-high transitions at the appropriate clock (CLKAB or CLKBA) terminals, regardless of the select- or output-control terminals. When SAB and SBA are in the real-time transfer mode, it is possible to store data without using the internal D-type flip-flops by simultaneously enabling OEAB and OEBA. In this configuration, each output reinforces its input. When all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

To ensure the high-impedance state during power up or power down, OEBA should be tied to V_{CC} through a pullup resistor, and OEAB should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

FUNCTION TABLE

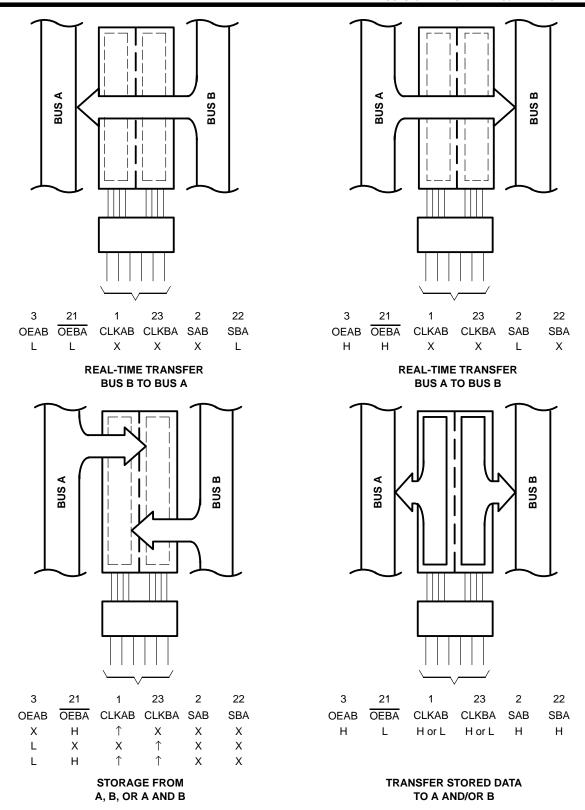
		INPU ⁻	гѕ			DATA	y 1/0‡	OPERATION OR FUNCTION
OEAB	OEBA	CLKAB	CLKBA	SAB	SBA	A1–A8	B1-B8	OPERATION OR FUNCTION
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation
L	Н	\uparrow	\uparrow	X	X	Input	Input	Store A and B data
Х	Н	↑	H or L	Х	Х	Input	Unspecified [‡]	Store A, hold B
Н	Н	\uparrow	\uparrow	X‡	X	Input	Output	Store A in both registers
L	Х	H or L	1	Х	Х	Unspecified [‡]	Input	Hold A, store B
L	L	\uparrow	1	X	X ‡	Output	Input	Store B in both registers
L	L	Χ	Х	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	X	Н	Output	Input	Stored B data to A bus
Н	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
Н	Н	H or L	Χ	Н	X	Input	Output	Stored A data to B bus
Н	L	H or L	H or L	Н	Н	Output Output		Stored A data to B bus and stored B data to A bus

The data-output functions are enabled or disabled by a variety of level combinations at OEAB or OEBA. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition on the clock inputs.



[‡] Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered to load both registers.

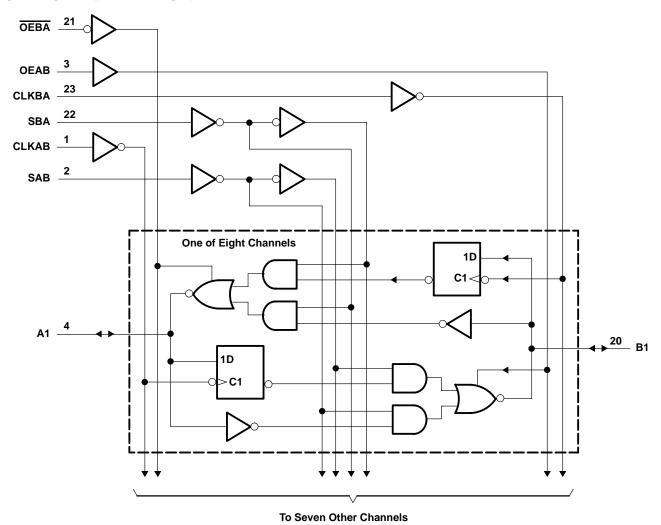


Pin numbers shown are for the DW, JT, NT, and W packages.

Figure 1. Bus-Management Functions



logic diagram (positive logic)



Pin numbers shown are for the DW, JT, NT, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC}) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	46°C/W
(see Note 3): NT package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-3.



recommended operating conditions (see Note 4)

			SN	154HC65	52	SN	174HC65	2	UNIT	
			MIN	NOM	MAX	MIN	NOM	MAX	UNII	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V _{CC} = 2 V	1.5			1.5				
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15		7	3.15			V	
		VCC = 6 V	4.2		<.	4.2				
		V _{CC} = 2 V		PEL	0.5			0.5		
VIL	Low-level input voltage	V _{CC} = 4.5 V		1.35				1.35	V	
		VCC = 6 V		0	1.8			1.8		
٧ı	Input voltage		0	7	VCC	0		VCC	V	
٧o	Output voltage		0		VCC	0		VCC	V	
		V _{CC} = 2 V			1000			1000		
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns	
		VCC = 6 V		400				400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NOTIONS		Т	A = 25°C	;	SN54H	C652	SN74F	IC652	UNIT
PAR	AMETER	lesi co	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
				2 V	1.9	1.998		1.9		1.9		
			I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		
Vон		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	i'h	5.34		
				2 V		0.002	0.1		0.1		0.1	
		V _I = V _{IH} or V _{IL}	$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	<	0.1		0.1	
V_{OL}				6 V		0.001	0.1	ó	0.1		0.1	V
			I _{OL} = 6 mA	4.5 V		0.17	0.26	20	0.4		0.33	
			I _{OL} = 7.8 mA	6 V		0.15	0.26	% 0	0.4		0.33	
lį	Control inputs	$V_I = V_{CC}$ or 0		6 V		±0.1	±100	4	±1000		±1000	nA
loz	A or B	VO = VCC or GN	D	6 V		±0.01	±0.5		±10		±5	μΑ
Icc	-	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci	Control inputs			2 V to 6 V		3	10		10		10	pF

SN54HC652, SN74HC652 OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	T _A = 1	25°C	SN54F	IC652	SN74H	IC652	UNIT
		VCC	MIN	MAX	MIN	MAX	MIN	MAX	UNII
		2 V		6		4.3		5.5	
fclock	Clock frequency	4.5 V		31		22		27	MHz
		6 V		36		25		31	
		2 V	80		115	, N	95		
t _W	Pulse duration, CLKBA or CLKAB high or low		16		23	77	19		ns
		6 V	14		20		16		
		2 V	100		150		125		
t _{su}	Setup time, A before CLKAB↑ or B before CLKBA↑	4.5 V	20		30		25		ns
		6 V	17		26		21		
		2 V	5		5		5		
th	Hold time, A after CLKAB↑ or B after CLKBA↑	4.5 V	5		5		5		ns
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 2)

242445752	FROM	то		T,	4 = 25°C	;	SN54F	IC652	SN74F	IC652	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	10		4.3		5.5		
f _{max}			4.5 V	31	40		22		27		MHz
			6 V	36	45		25		31		
			2 V		65	180		270		225	
	CLKBA or CLKAB	A or B	4.5 V		18	36		54		45	
			6 V		14	31		46		38	
			2 V		50	135		205		170	
^t pd	A or B	B or A	4.5 V		14	27		41		34	ns
			6 V		11	23		35		29	
			2 V		70	190	4	285		240	
	SBA or SAB†	A or B	4.5 V		20	38	25	57		48	
			6 V		16	32	0	48		41	
			2 V		85	245	0	370		305	
t _{en}	OEBA or OEAB	A or B	4.5 V		25	49		74		61	ns
			6 V		20	42		63		52	
			2 V		50	245		370		305	
^t dis	OEBA or OEAB	A or B	4.5 V		23	49		74		61	ns
aio			6 V		20	42		63		52	
			2 V		28	60		90		75	
t _t		Any	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.



switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 2)

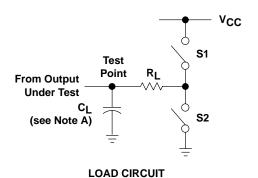
PARAMETER	FROM	то	V	T,	գ = 25°C	;	SN54H	IC652	SN74H	C652	UNIT											
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII											
			2 V		90	265		400		330												
	CLKBA or CLKAB	A or B	4.5 V		24	53		80		66												
			6 V		18	46		68		57												
			2 V		70	220		335		275												
t _{pd}	A or B	B or A	4.5 V		20	44		70		55	ns											
			6 V		15	38		57		48												
			2 V		80	275	6	415		345												
	SBA or SAB†	A or B	A or B	A or B	4.5 V		24	55	70	83		69										
			6 V		20	47	50	70		60												
			2 V		100	330	Q	500		410												
t _{en}	OEBA or OEAB	A or B	4.5 V		33	66		100		82	ns											
			6 V		27	57		85		71												
			2 V		45	210		315		265												
t _t		Any	Any	Any	Any	Any	Any	Any	Any	Any	Any	Any	Any	4.5 V		17	42		63		53	ns
			6 V		13	36		53		43												

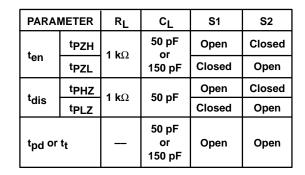
[†] These parameters are measured with the internal output state of the storage register opposite that of the bus input.

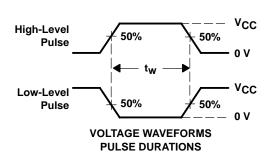
operating characteristics, $T_A = 25^{\circ}C$

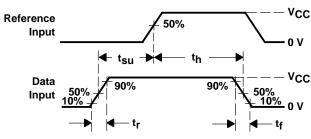
	PARAMETER	TEST CONDITIONS	TYP	UNIT
Γ	C _{pd} Power dissipation capacitance	No load	50	pF

PARAMETER MEASUREMENT INFORMATION

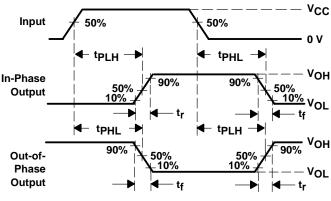


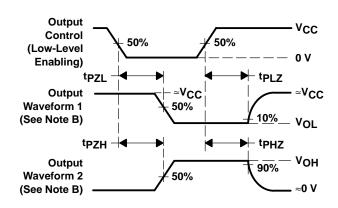






VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLz and tpHz are the same as tdis.
- G. tpZL and tpZH are the same as ten.
- H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC652DW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	-40 to 85	HC652	
SN74HC652DWR	ACTIVE	SOIC	DW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC652	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC652DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
I	SN74HC652DWR	SOIC	DW	24	2000	350.0	350.0	43.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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